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Intel - EP20K200BC356-2 Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	832
Number of Logic Elements/Cells	8320
Total RAM Bits	106496
Number of I/O	277
Number of Gates	526000
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	356-LBGA
Supplier Device Package	356-BGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k200bc356-2

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All APEX 20K devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault coverage purposes. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different application-specific integrated circuit (ASIC) designs; APEX 20K devices can be configured on the board for the specific functionality required.

APEX 20K devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable EPC1, EPC2, and EPC16 configuration devices, which configure APEX 20K devices via a serial data stream. Moreover, APEX 20K devices contain an optimized interface that permits microprocessors to configure APEX 20K devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat APEX 20K devices as memory and configure the device by writing to a virtual memory location, making reconfiguration easy.

After an APEX 20K device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

APEX 20K devices are supported by the Altera Quartus II development system, a single, integrated package that offers HDL and schematic design entry, compilation and logic synthesis, full simulation and worst-case timing analysis, SignalTap logic analysis, and device configuration. The Quartus II software runs on Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations.

The Quartus II software provides NativeLink interfaces to other industrystandard PC- and UNIX workstation-based EDA tools. For example, designers can invoke the Quartus II software from within third-party design tools. Further, the Quartus II software contains built-in optimized synthesis libraries; synthesis tools can use these libraries to optimize designs for APEX 20K devices. For example, the Synopsys Design Compiler library, supplied with the Quartus II development system, includes DesignWare functions optimized for the APEX 20K architecture.

Logic Array Block

Each LAB consists of 10 LEs, the LEs' associated carry and cascade chains, LAB control signals, and the local interconnect. The local interconnect transfers signals between LEs in the same or adjacent LABs, IOEs, or ESBs. The Quartus II Compiler places associated logic within an LAB or adjacent LABs, allowing the use of a fast local interconnect for high performance. Figure 3 shows the APEX 20K LAB.

APEX 20K devices use an interleaved LAB structure. This structure allows each LE to drive two local interconnect areas. This feature minimizes use of the MegaLAB and FastTrack interconnect, providing higher performance and flexibility. Each LE can drive 29 other LEs through the fast local interconnect.







Figure 6. APEX 20K Carry Chain

Table 9. APEX 20K Routing Scheme											
Source	Destination										
	Row I/O Pin	Column I/O Pin	LE	ESB	Local Interconnect	MegaLAB Interconnect	Row FastTrack Interconnect	Column FastTrack Interconnect	FastRow Interconnect		
Row I/O Pin					✓	~	~	~			
Column I/O Pin								~	✓ (1)		
LE					~	~	~	~			
ESB					 Image: A set of the set of the	~	~	~			
Local Interconnect	~	~	~	~							
MegaLAB Interconnect					~						
Row FastTrack Interconnect						~		~			
Column FastTrack Interconnect						~	~				
FastRow Interconnect					✓ (1)						

Note to Table 9:

(1) This connection is supported in APEX 20KE devices only.

Product-Term Logic

The product-term portion of the MultiCore architecture is implemented with the ESB. The ESB can be configured to act as a block of macrocells on an ESB-by-ESB basis. Each ESB is fed by 32 inputs from the adjacent local interconnect; therefore, it can be driven by the MegaLAB interconnect or the adjacent LAB. Also, nine ESB macrocells feed back into the ESB through the local interconnect for higher performance. Dedicated clock pins, global signals, and additional inputs from the local interconnect drive the ESB control signals.

In product-term mode, each ESB contains 16 macrocells. Each macrocell consists of two product terms and a programmable register. Figure 13 shows the ESB in product-term mode.



Figure 22. ESB in Single-Port Mode Note (1)

Notes to Figure 22:

All registers can be asynchronously cleared by ESB local interconnect signals, global signals, or the chip-wide reset.
 APEX 20KE devices have four dedicated clocks.

Content-Addressable Memory

In APEX 20KE devices, the ESB can implement CAM. CAM can be thought of as the inverse of RAM. When read, RAM outputs the data for a given address. Conversely, CAM outputs an address for a given data word. For example, if the data FA12 is stored in address 14, the CAM outputs 14 when FA12 is driven into it.

CAM is used for high-speed search operations. When searching for data within a RAM block, the search is performed serially. Thus, finding a particular data word can take many cycles. CAM searches all addresses in parallel and outputs the address storing a particular word. When a match is found, a match flag is set high. Figure 23 shows the CAM block diagram.



For more information on APEX 20KE devices and CAM, see *Application* Note 119 (Implementing High-Speed Search Applications with APEX CAM).

Driving Signals to the ESB

ESBs provide flexible options for driving control signals. Different clocks can be used for the ESB inputs and outputs. Registers can be inserted independently on the data input, data output, read address, write address, WE, and RE signals. The global signals and the local interconnect can drive the WE and RE signals. The global signals, dedicated clock pins, and local interconnect can drive the ESB clock signals. Because the LEs drive the local interconnect, the LEs can control the WE and RE signals and the ESB clock, clock enable, and asynchronous clear signals. Figure 24 shows the ESB control signal generation logic.





(1) APEX 20KE devices have four dedicated clocks.

An ESB is fed by the local interconnect, which is driven by adjacent LEs (for high-speed connection to the ESB) or the MegaLAB interconnect. The ESB can drive the local, MegaLAB, or FastTrack Interconnect routing structure to drive LEs and IOEs in the same MegaLAB structure or anywhere in the device.

Under hot socketing conditions, APEX 20KE devices will not sustain any damage, but the I/O pins will drive out.

MultiVolt I/O Interface

The APEX device architecture supports the MultiVolt I/O interface feature, which allows APEX devices in all packages to interface with systems of different supply voltages. The devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The APEX 20K VCCINT pins must always be connected to a 2.5 V power supply. With a 2.5-V V_{CCINT} level, input pins are 2.5-V, 3.3-V, and 5.0-V tolerant. The VCCIO pins can be connected to either a 2.5-V or 3.3-V power supply, depending on the output requirements. When VCCIO pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When the VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3 V and is compatible with 3.3-V or 5.0-V systems.

Table 12. 5.0-V Tolerant APEX 20K MultiVolt I/O Support										
V _{CCIO} (V)	Input Signals (V) Output Signals (V)									
	2.5	3.3	5.0	2.5	3.3	5.0				
2.5	\checkmark	√ (1)	✓(1)	~						
3.3	\checkmark	 Image: A set of the set of the	√ (1)	√ (2)	>	 Image: A set of the set of the				

Table 12 summarizes 5.0-V tolerant APEX 20K MultiVolt I/O support.

Notes to Table 12:

- The PCI clamping diode must be disabled to drive an input with voltages higher than V_{CCIO}.
- (2) When $V_{CCIO} = 3.3 \text{ V}$, an APEX 20K device can drive a 2.5-V device with 3.3-V tolerant inputs.

Open-drain output pins on 5.0-V tolerant APEX 20K devices (with a pullup resistor to the 5.0-V supply) can drive 5.0-V CMOS input pins that require a V_{IH} of 3.5 V. When the pin is inactive, the trace will be pulled up to 5.0 V by the resistor. The open-drain pin will only drive low or tri-state; it will never drive high. The rise time is dependent on the value of the pullup resistor and load impedance. The I_{OL} current specification should be considered when selecting a pull-up resistor. For designs that require both a multiplied and non-multiplied clock, the clock trace on the board can be connected to CLK2p. Table 14 shows the combinations supported by the ClockLock and ClockBoost circuitry. The CLK2p pin can feed both the ClockLock and ClockBoost circuitry in the APEX 20K device. However, when both circuits are used, the other clock pin (CLK1p) cannot be used.

Table 14. Multiplication Factor Combinations						
Clock 1	Clock 2					
×1	×1					
×1, ×2	×2					
×1, ×2, ×4	×4					

APEX 20KE ClockLock Feature

APEX 20KE devices include an enhanced ClockLock feature set. These devices include up to four PLLs, which can be used independently. Two PLLs are designed for either general-purpose use or LVDS use (on devices that support LVDS I/O pins). The remaining two PLLs are designed for general-purpose use. The EP20K200E and smaller devices have two PLLs; the EP20K300E and larger devices have four PLLs.

The following sections describe some of the features offered by the APEX 20KE PLLs.

External PLL Feedback

The ClockLock circuit's output can be driven off-chip to clock other devices in the system; further, the feedback loop of the PLL can be routed off-chip. This feature allows the designer to exercise fine control over the I/O interface between the APEX 20KE device and another high-speed device, such as SDRAM.

Clock Multiplication

The APEX 20KE ClockBoost circuit can multiply or divide clocks by a programmable number. The clock can be multiplied by $m/(n \times k)$ or $m/(n \times v)$, where *m* and *k* range from 2 to 160, and *n* and *v* range from 1 to 16. Clock multiplication and division can be used for time-domain multiplexing and other functions, which can reduce design LE requirements.

Notes to Table 16:

- (1) To implement the ClockLock and ClockBoost circuitry with the Quartus II software, designers must specify the input frequency. The Quartus II software tunes the PLL in the ClockLock and ClockBoost circuitry to this frequency. The *f_{CLKDEV}* parameter specifies how much the incoming clock can differ from the specified frequency during device operation. Simulation does not reflect this parameter.
- (2) Twenty-five thousand parts per million (PPM) equates to 2.5% of input clock period.
- (3) During device configuration, the ClockLock and ClockBoost circuitry is configured before the rest of the device. If the incoming clock is supplied during configuration, the ClockLock and ClockBoost circuitry locks during configuration because the t_{LOCK} value is less than the time required for configuration.
- (4) The t_{IITTER} specification is measured under long-term observation.

Tables 17 and 18 summarize the ClockLock and ClockBoost parameters for APEX 20KE devices.

Table 17. APEX 20KE ClockLock & ClockBoost Parameters Note (1)											
Symbol	Parameter	Conditions	Min	Тур	Max	Unit					
t _R	Input rise time				5	ns					
t _F	Input fall time				5	ns					
t _{INDUTY}	Input duty cycle		40		60	%					
t _{INJITTER}	Input jitter peak-to-peak				2% of input period	peak-to- peak					
	Jitter on ClockLock or ClockBoost- generated clock				0.35% of output period	RMS					
t _{outduty}	Duty cycle for ClockLock or ClockBoost-generated clock		45		55	%					
t _{LOCK} <i>(2)_, (3)</i>	Time required for ClockLock or ClockBoost to acquire lock				40	μs					

Table 18. A	PEX 20KE Clock Input & Out	put Parameters	(Part 1	of 2) Note	e (1)		
Symbol	Parameter	I/O Standard	-1X Spe	ed Grade	-2X Speed	l Grade	Units
			Min	Max	Min	Max	
f _{VCO} (4)	Voltage controlled oscillator operating range		200	500	200	500	MHz
f _{CLOCK0}	Clock0 PLL output frequency for internal use		1.5	335	1.5	200	MHz
f _{CLOCK1}	Clock1 PLL output frequency for internal use		20	335	20	200	MHz
f _{CLOCK0_EXT}	Output clock frequency for	3.3-V LVTTL	1.5	245	1.5	226	MHz
	external clock0 output	2.5-V LVTTL	1.5	234	1.5	221	MHz
		1.8-V LVTTL	1.5	223	1.5	216	MHz
		GTL+	1.5	205	1.5	193	MHz
		SSTL-2 Class I	1.5	158	1.5	157	MHz
		SSTL-2 Class II	1.5	142	1.5	142	MHz
		SSTL-3 Class I	1.5	166	1.5	162	MHz
		SSTL-3 Class II	1.5	149	1.5	146	MHz
		LVDS	1.5	420	1.5	350	MHz
f _{CLOCK1_EXT}	Output clock frequency for	3.3-V LVTTL	20	245	20	226	MHz
	external clock1 output	2.5-V LVTTL	20	234	20	221	MHz
		1.8-V LVTTL	20	223	20	216	MHz
		GTL+	20	205	20	193	MHz
		SSTL-2 Class I	20	158	20	157	MHz
		SSTL-2 Class II	20	142	20	142	MHz
		SSTL-3 Class I	20	166	20	162	MHz
		SSTL-3 Class II	20	149	20	146	MHz
		LVDS	20	420	20	350	MHz

Tadie 21. 32-Bit	I AUIG 2 1. 32-DII AFEA 20K DEVICE IDGUDE											
Device	IDCODE (32 Bits) (1)											
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer Identity (11 Bits)	1 (1 Bit) (2)								
EP20K30E	0000	1000 0000 0011 0000	000 0110 1110	1								
EP20K60E	0000	1000 0000 0110 0000	000 0110 1110	1								
EP20K100	0000	0000 0100 0001 0110	000 0110 1110	1								
EP20K100E	0000	1000 0001 0000 0000	000 0110 1110	1								
EP20K160E	0000	1000 0001 0110 0000	000 0110 1110	1								
EP20K200	0000	0000 1000 0011 0010	000 0110 1110	1								
EP20K200E	0000	1000 0010 0000 0000	000 0110 1110	1								
EP20K300E	0000	1000 0011 0000 0000	000 0110 1110	1								
EP20K400	0000	0001 0110 0110 0100	000 0110 1110	1								
EP20K400E	0000	1000 0100 0000 0000	000 0110 1110	1								
EP20K600E	0000	1000 0110 0000 0000	000 0110 1110	1								
EP20K1000E	0000	1001 0000 0000 0000	000 0110 1110	1								

11- 04 00 04 4 ~

Notes to Table 21:

The most significant bit (MSB) is on the left. (1)

(2) The IDCODE's least significant bit (LSB) is always 1.

Figure 31 shows the timing requirements for the JTAG signals.





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Figures 38 and 39 show the asynchronous and synchronous timing waveforms, respectively, for the ESB macroparameters in Table 31.



Figure 38. ESB Asynchronous Timing Waveforms

Figure 39. ESB Synchronous Timing Waveforms



ESB Synchronous Write (ESB Output Registers Used)



Figure 40 shows the timing model for bidirectional I/O pin timing.

Symbol	-1 Spee	-1 Speed Grade		d Grade	-3 Spee	-3 Speed Grade	
	Min	Max	Min	Max	Min	Max	
t _{SU}	0.1		0.3		0.6		ns
t _H	0.5		0.8		0.9		ns
t _{CO}		0.1		0.4		0.6	ns
t _{LUT}		1.0		1.2		1.4	ns
t _{ESBRC}		1.7		2.1		2.4	ns
t _{ESBWC}		5.7		6.9		8.1	ns
t _{ESBWESU}	3.3		3.9		4.6		ns
t _{ESBDATASU}	2.2		2.7		3.1		ns
t _{ESBDATAH}	0.6		0.8		0.9		ns
t _{ESBADDRSU}	2.4		2.9		3.3		ns
t _{ESBDATACO1}		1.3		1.6		1.8	ns
t _{ESBDATACO2}		2.5		3.1		3.6	ns
t _{ESBDD}		2.5		3.3		3.6	ns
t _{PD}		2.5		3.1		3.6	ns
t _{PTERMSU}	1.7		2.1		2.4		ns
t _{PTERMCO}		1.0		1.2		1.4	ns
t _{F1-4}		0.4		0.5		0.6	ns
t _{F5-20}		2.6		2.8		2.9	ns
t _{F20+}		3.7		3.8		3.9	ns
t _{CH}	2.0		2.5		3.0		ns
t _{CL}	2.0		2.5		3.0		ns
t _{CLRP}	0.5		0.6		0.8		ns
t _{PREP}	0.5		0.5		0.5		ns
t _{ESBCH}	2.0		2.5		3.0		ns
t _{ESBCL}	2.0		2.5		3.0		ns
t _{ESBWP}	1.5		1.9		2.2		ns
t _{ESBRP}	1.0		1.2		1.4		ns

Tables 43 through 48 show the I/O external and external bidirectional timing parameter values for EP20K100, EP20K200, and EP20K400 APEX 20K devices.

Notes to Tables 43 through 48:

- (1) This parameter is measured without using ClockLock or ClockBoost circuits.
- (2) This parameter is measured using ClockLock or ClockBoost circuits.

Tables 49 through 54 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K30E APEX 20KE devices.

Table 49. EP20K30E f _{MAX} LE Timing Microparameters										
Symbol	-1 -2			-	Unit					
	Min	Max	Min	Max	Min	Max				
t _{SU}	0.01		0.02		0.02		ns			
t _H	0.11		0.16		0.23		ns			
t _{CO}		0.32		0.45		0.67	ns			
t _{LUT}		0.85		1.20		1.77	ns			

Table 69. EP20K160E f _{MAX} Routing Delays										
Symbol		-1	1 -2		-3		Unit			
	Min	Max	Min	Max	Min	Max				
t _{F1-4}		0.25		0.26		0.28	ns			
t _{F5-20}		1.00		1.18		1.35	ns			
t _{F20+}		1.95		2.19		2.30	ns			

Symbol	-	1	-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{CH}	1.34		1.43		1.55		ns
t _{CL}	1.34		1.43		1.55		ns
t _{CLRP}	0.18		0.19		0.21		ns
t _{PREP}	0.18		0.19		0.21		ns
t _{ESBCH}	1.34		1.43		1.55		ns
t _{ESBCL}	1.34		1.43		1.55		ns
t _{ESBWP}	1.15		1.45		1.73		ns
t _{ESBRP}	0.93		1.15		1.38		ns

Table 71. EP20K160E External Timing Parameters										
Symbol	-1			-2		-3				
	Min	Max	Min	Max	Min	Max				
t _{INSU}	2.23		2.34		2.47		ns			
t _{INH}	0.00		0.00		0.00		ns			
t _{outco}	2.00	5.07	2.00	5.59	2.00	6.13	ns			
t _{insupll}	2.12		2.07		-		ns			
t _{INHPLL}	0.00		0.00		-		ns			
t _{outcopll}	0.50	3.00	0.50	3.35	-	-	ns			

Table 74. EP20K200E f _{MAX} ESB Timing Microparameters							
Symbol	-1		-2		-3		Unit
	Min	Мах	Min	Мах	Min	Max	
t _{ESBARC}		1.68		2.06		2.24	ns
t _{ESBSRC}		2.27		2.77		3.18	ns
t _{ESBAWC}		3.10		3.86		4.50	ns
t _{ESBSWC}		2.90		3.67		4.21	ns
t _{ESBWASU}	0.55		0.67		0.74		ns
t _{ESBWAH}	0.36		0.46		0.48		ns
t _{ESBWDSU}	0.69		0.83		0.95		ns
t _{ESBWDH}	0.36		0.46		0.48		ns
t _{ESBRASU}	1.61		1.90		2.09		ns
t _{ESBRAH}	0.00		0.00		0.01		ns
t _{ESBWESU}	1.42		1.71		2.01		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.06		-0.07		0.05		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.11		0.13		0.31		ns
t _{ESBRADDRSU}	0.18		0.23		0.39		ns
t _{ESBDATACO1}		1.09		1.35		1.51	ns
t _{ESBDATACO2}		2.19		2.75		3.22	ns
t _{ESBDD}		2.75		3.41		4.03	ns
t _{PD}		1.58		1.97		2.33	ns
t _{PTERMSU}	1.00		1.22		1.51		ns
t _{PTERMCO}		1.10		1.37		1.09	ns

Table 75. EP20K200E f _{MAX} Routing Delays							
Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{F1-4}		0.25		0.27		0.29	ns
t _{F5-20}		1.02		1.20		1.41	ns
t _{F20+}		1.99		2.23		2.53	ns

Table 80. EP20K300E f _{MAX} ESB Timing Microparameters							
Symbol	-	1		-2	-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.79		2.44		3.25	ns
t _{ESBSRC}		2.40		3.12		4.01	ns
t _{ESBAWC}		3.41		4.65		6.20	ns
t _{ESBSWC}		3.68		4.68		5.93	ns
t _{ESBWASU}	1.55		2.12		2.83		ns
t _{ESBWAH}	0.00		0.00		0.00		ns
t _{ESBWDSU}	1.71		2.33		3.11		ns
t _{ESBWDH}	0.00		0.00		0.00		ns
t _{ESBRASU}	1.72		2.34		3.13		ns
t _{ESBRAH}	0.00		0.00		0.00		ns
t _{ESBWESU}	1.63		2.36		3.28		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	0.07		0.39		0.80		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.27		0.67		1.17		ns
t _{ESBRADDRSU}	0.34		0.75		1.28		ns
t _{ESBDATACO1}		1.03		1.20		1.40	ns
t _{ESBDATACO2}		2.33		3.18		4.24	ns
t _{ESBDD}		3.41		4.65		6.20	ns
t _{PD}		1.68		2.29		3.06	ns
t _{PTERMSU}	0.96		1.48		2.14		ns
t _{PTERMCO}		1.05		1.22		1.42	ns

Table 81. EP20K300E f _{MAX} Routing Delays							
Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{F1-4}		0.22		0.24		0.26	ns
t _{F5-20}		1.33		1.43		1.58	ns
t _{F20+}		3.63		3.93		4.35	ns

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Table 87. EP20K400E f _{MAX} Routing Delays							
Symbol	-1 Speed Grade		-2 Spe	-2 Speed Grade		d Grade	Unit
	Min	Max	Min	Max	Min	Max	
t _{F1-4}		0.25		0.25		0.26	ns
t _{F5-20}		1.01		1.12		1.25	ns
t _{F20+}		3.71		3.92		4.17	ns

Symbol	ol -1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{CH}	1.36		2.22		2.35		ns
t _{CL}	1.36		2.26		2.35		ns
t _{CLRP}	0.18		0.18		0.19		ns
t _{PREP}	0.18		0.18		0.19		ns
t _{ESBCH}	1.36		2.26		2.35		ns
t _{ESBCL}	1.36		2.26		2.35		ns
t _{ESBWP}	1.17		1.38		1.56		ns
t _{ESBRP}	0.94		1.09		1.25		ns

Table 89. EP20K400E External Timing Parameters							
Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.51		2.64		2.77		ns
t _{INH}	0.00		0.00		0.00		ns
t _{outco}	2.00	5.25	2.00	5.79	2.00	6.32	ns
t _{insupll}	3.221		3.38		-		ns
t _{INHPLL}	0.00		0.00		-		ns
t _{outcopll}	0.50	2.25	0.50	2.45	-	-	ns

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SRAM configuration elements allow APEX 20K devices to be reconfigured in-circuit by loading new configuration data into the device. Real-time reconfiguration is performed by forcing the device into command mode with a device pin, loading different configuration data, reinitializing the device, and resuming usermode operation. In-field upgrades can be performed by distributing new configuration files.

Configuration Schemes

The configuration data for an APEX 20K device can be loaded with one of five configuration schemes (see Table 111), chosen on the basis of the target application. An EPC2 or EPC16 configuration device, intelligent controller, or the JTAG port can be used to control the configuration of an APEX 20K device. When a configuration device is used, the system can configure automatically at system power-up.

Multiple APEX 20K devices can be configured in any of five configuration schemes by connecting the configuration enable (nCE) and configuration enable output (nCEO) pins on each device.

Table 111. Data Sources for Configuration					
Configuration Scheme	Data Source				
Configuration device	EPC1, EPC2, EPC16 configuration devices				
Passive serial (PS)	MasterBlaster or ByteBlasterMV download cable or serial data source				
Passive parallel asynchronous (PPA)	Parallel data source				
Passive parallel synchronous (PPS)	Parallel data source				
JTAG	MasterBlaster or ByteBlasterMV download cable or a microprocessor with a Jam or JBC File				



For more information on configuration, see *Application Note* 116 (*Configuring APEX 20K, FLEX 10K, & FLEX 6000 Devices.*)

Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information